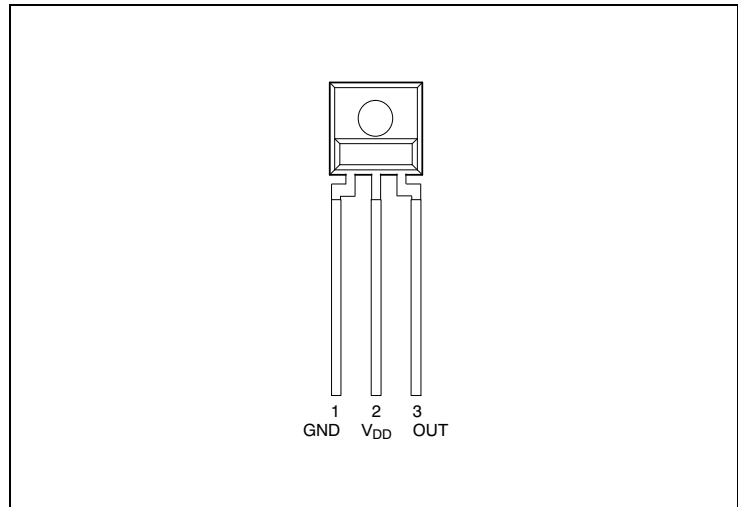


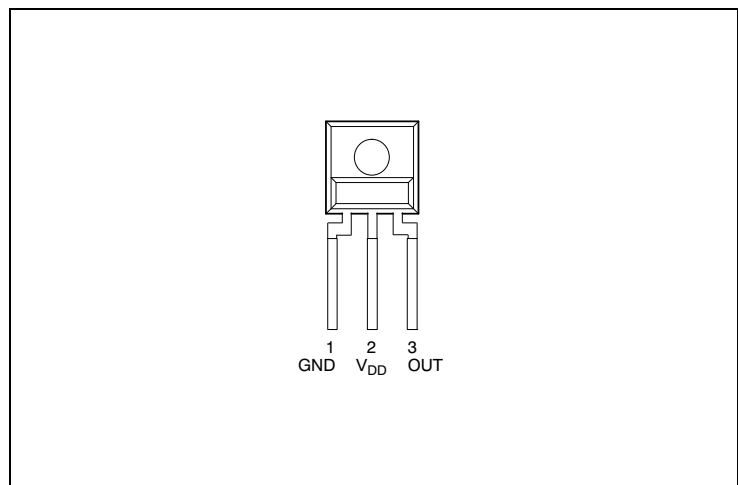
## Pin Assignment

The TSL257 pin assignments are described below.

**Figure 3:**  
Pin Diagram of Package S Sidelooker (Front View)



**Figure 4:**  
Pin Diagram of Package SM Surface Mount Sidelooker (Front View)



**Figure 5:**  
Terminal Functions

Terminal		Description
No.	Name	
1	GND	Ground (substrate). All voltages are referenced to GND.
2	V <sub>DD</sub>	Supply voltage
3	OUT	Output voltage

## Absolute Maximum Ratings

Stresses beyond those listed under [Absolute Maximum Ratings](#) may cause permanent damage to the device. These are stress ratings only. Functional operation of the device at these or any other conditions beyond those indicated under [Operating Conditions](#) is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

**Figure 6:**  
**Absolute Maximum Ratings over Operating Free-Air Temperature Range (unless otherwise noted)**

Symbol	Parameter	Min	Max	Unit
$V_{DD}$	Supply voltage <sup>(1)</sup>		6	V
$I_O$	Output current		±10	mA
	Duration of short-circuit current at (or below) 25°C		5	s
$T_A$	Operating free-air temperature range	-25	85	°C
$T_{STRG}$	Storage temperature range	-25	85	°C
	Lead temperature 1.6mm (1/16 inch) from case for 10 seconds (S Package)		260	°C
	Reflow solder, in accordance with J-STD-020C or J-STD-020D (SM Package)		260	°C

**Note(s):**

1. All voltages are with respect to GND.